



ENVIRO/Flow HAL-30

Product Description

ENVIRO/Flow HAL-30 is a low to medium viscosity hot air solder leveling flux designed to assure rapid and complete soldering of printed wiring boards. ENVIRO/Flow Hall-30 is a low acid formulation minimizing equipment wear.

Performance Features

- Removes copper oxides
- Deposits a non-evaporative film over the copper resulting in a stable, clean solderable copper surface
- Reduces the surface tension at the copper/solder interface resulting in excellent solder coverage and appearance free of solder tailings or solder webbing
- Does not contain glycol ethers or activators which could attack solder mask or laminate

Physical Specifications

Physical State	Liquid
Appearance	Transparent Light Amber
pH	< 2.5
Rinsability	Excellent
Freeze/Thaw Stability	Protect from freezing
Specific Gravity	1.1
Flash Point	>600 °F

Equipment Requirements

ENVIRO/Flow HAL-30 is compatible with all types of plastic, elastomers, and stainless steel employed by standard fluxing equipment. Hall-30 is not compatible with mild steel or aluminum.

Product Make-Up

ENVIRO/Flow HAL-30 is a ready to use product and should NOT be diluted.

Concentration and Application Method

ENVIRO/Flow HAL-30 can be applied with a standard flux applicator. It is not necessary to heat ENVIRO/Flow HAL-30 prior to use. The solution level should be maintained by adding fresh ENVIRO/Flow HAL-30.

Companion Products

Please see Seacole's Enviro/Etch products.

Safety and Handling

Please review and understand the ENVIRO/Flow HAL-30 SDS before handling.

Waste Treatment

Individual users should verify the nature of spent solutions to assure compliance with local, state, and federal regulations.

Ordering Information

ENVIRO/Flow HAL-30 is available in 5-gallon pails and 55-gallon drums.



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